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(12) **United States Design Patent**
Edmond et al.

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(54) **LED CHIP**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

(21) Appl. No.: **29/335,819**

(22) Filed: **Apr. 22, 2009**

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/180**

(58) **Field of Classification Search** D13/180;
D26/2; 257/79, 80, 81, 88, 89, 95, 98, 99,
257/100; 313/483, 498, 500; 362/555, 800
See application file for complete search history.

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Primary Examiner — Selina Sikder

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(57) **CLAIM**

The ornamental design for a LED chip, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of an LED chip showing our design;

FIG. 2 is a top view thereof;

FIG. 3 is a first side view thereof;

FIG. 4 is a bottom view thereof;

FIG. 5 is a different side view thereof;

FIG. 6 is an end view thereof;

FIG. 7 is an opposing end view thereof;

FIG. 8 is a top perspective view of the LED chip of FIG. 1 with the top surface removed;

FIG. 9 is a top view thereof;

FIG. 10 is a first side view thereof;

FIG. 11 is a bottom view thereof;

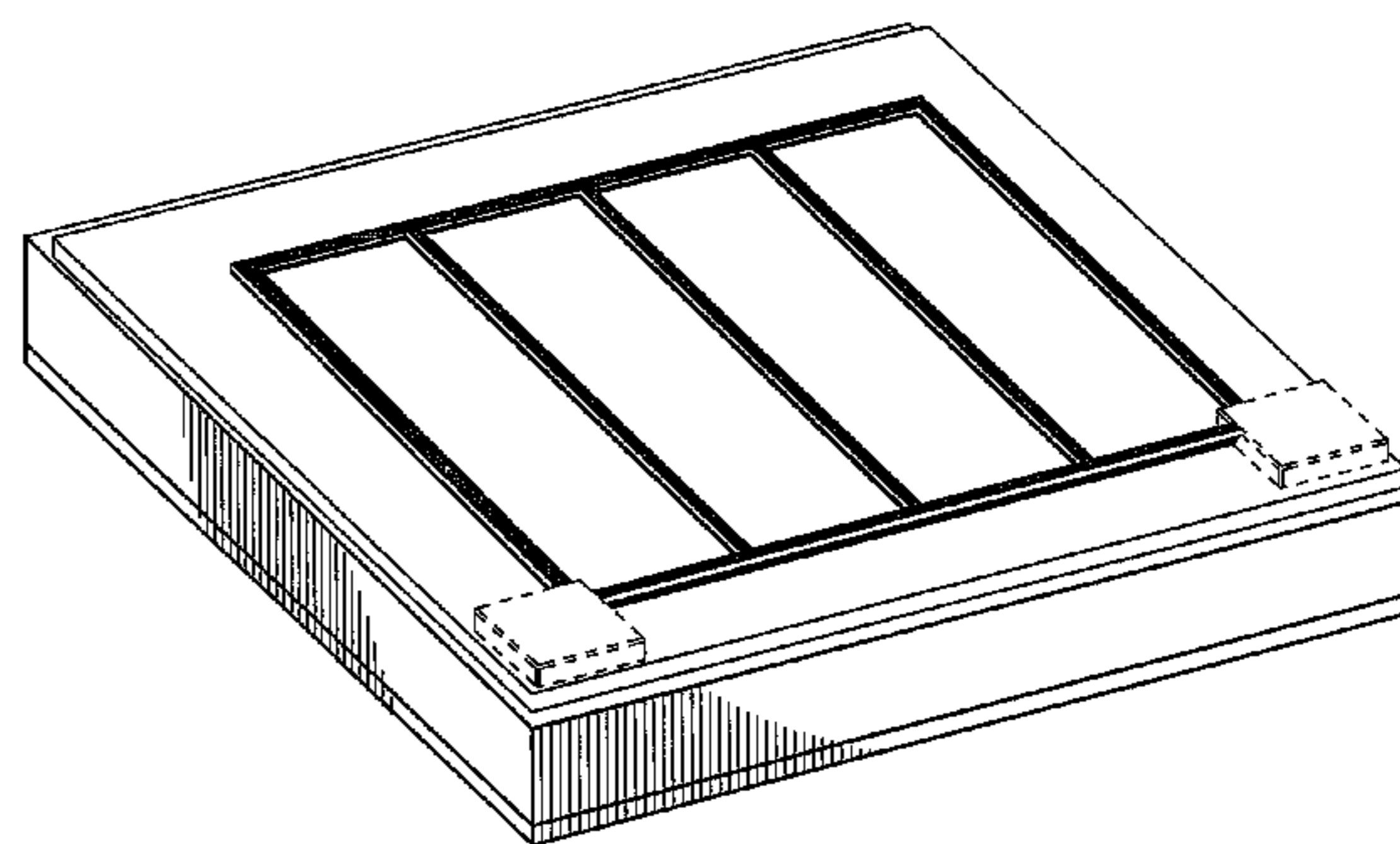
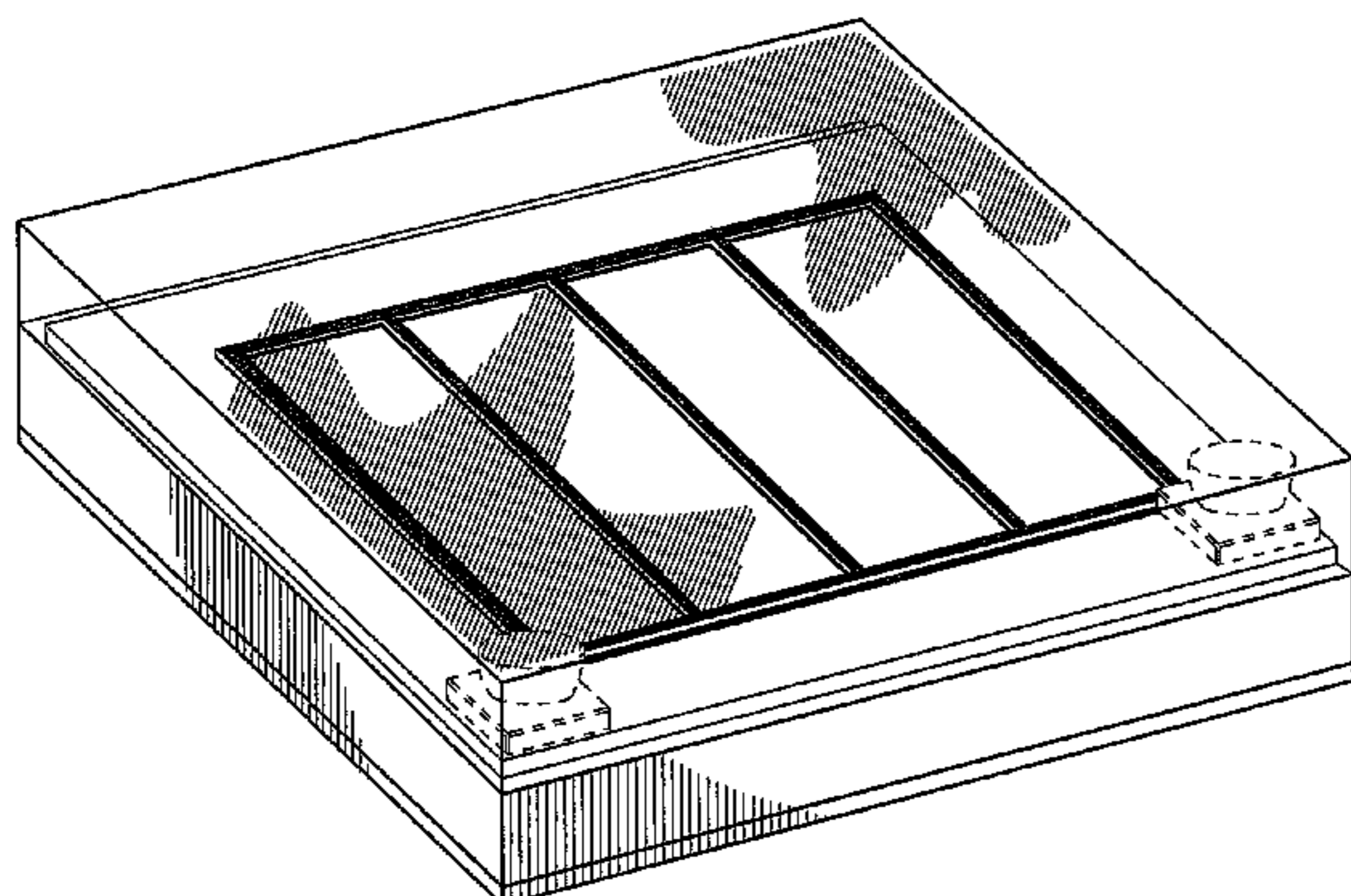
FIG. 12 is a different side view thereof;

FIG. 13 is an end view thereof; and,

FIG. 14 is an opposing end view thereof.

The broken lines define portions of the LED chip that form no part of the claimed design.

1 Claim, 4 Drawing Sheets



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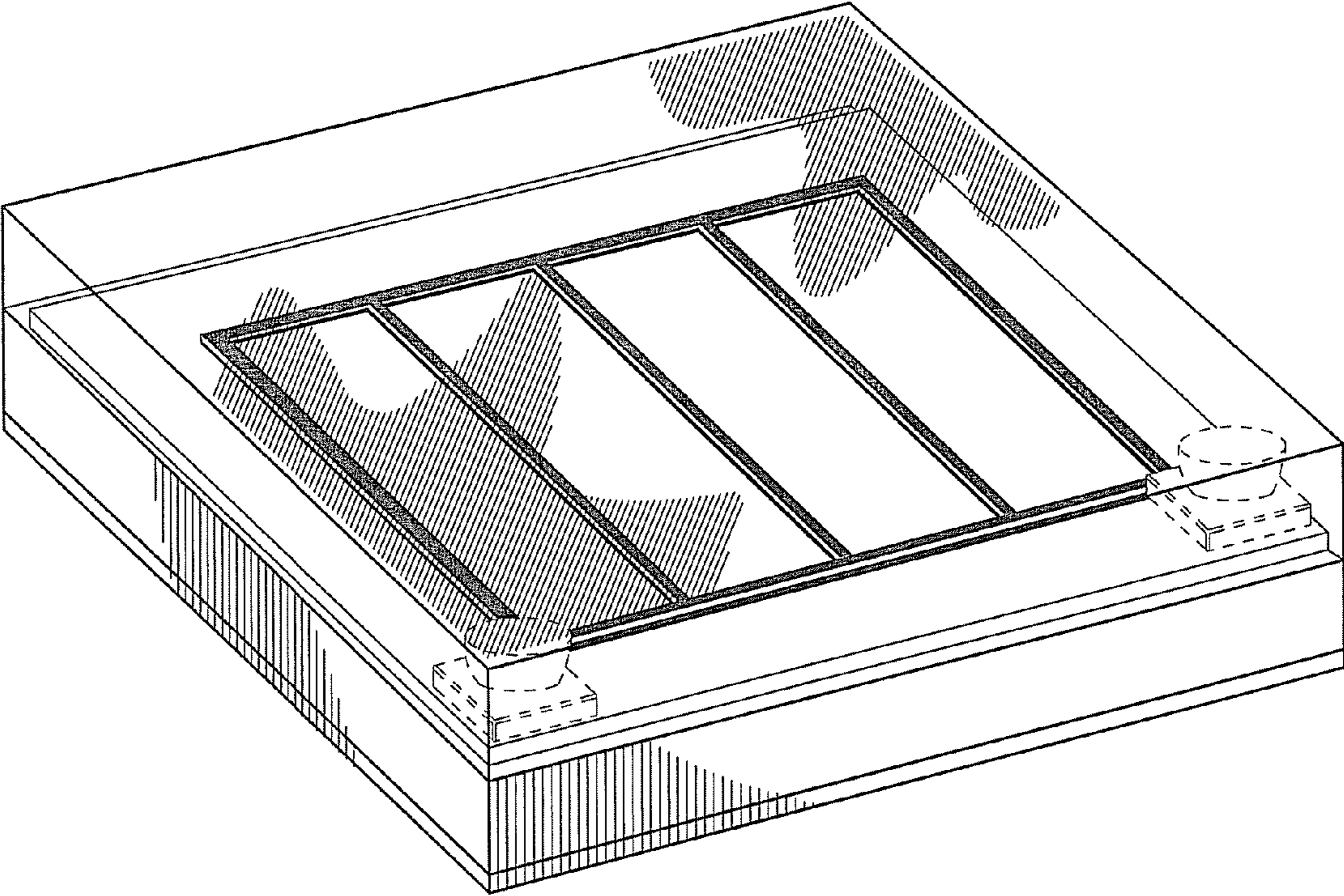


FIG. 1

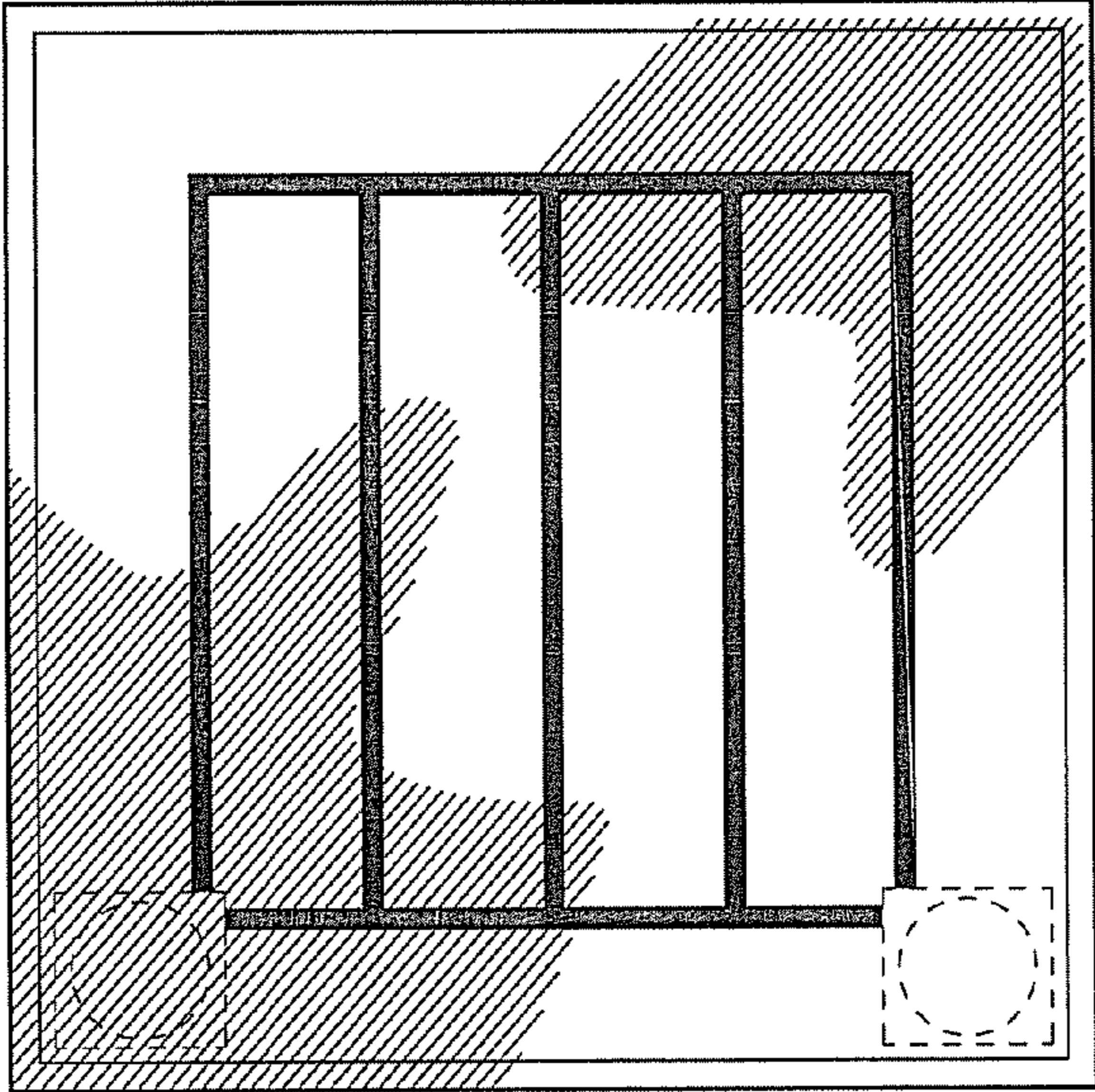


FIG. 2

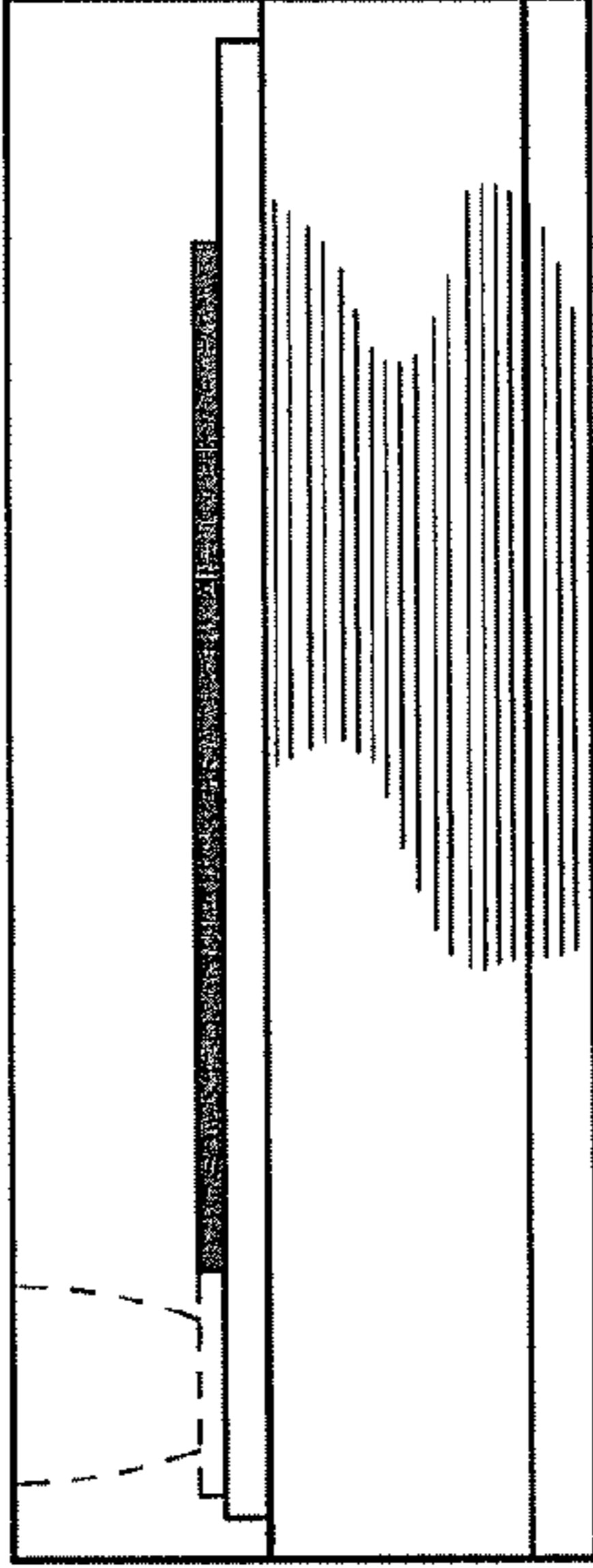


FIG. 3

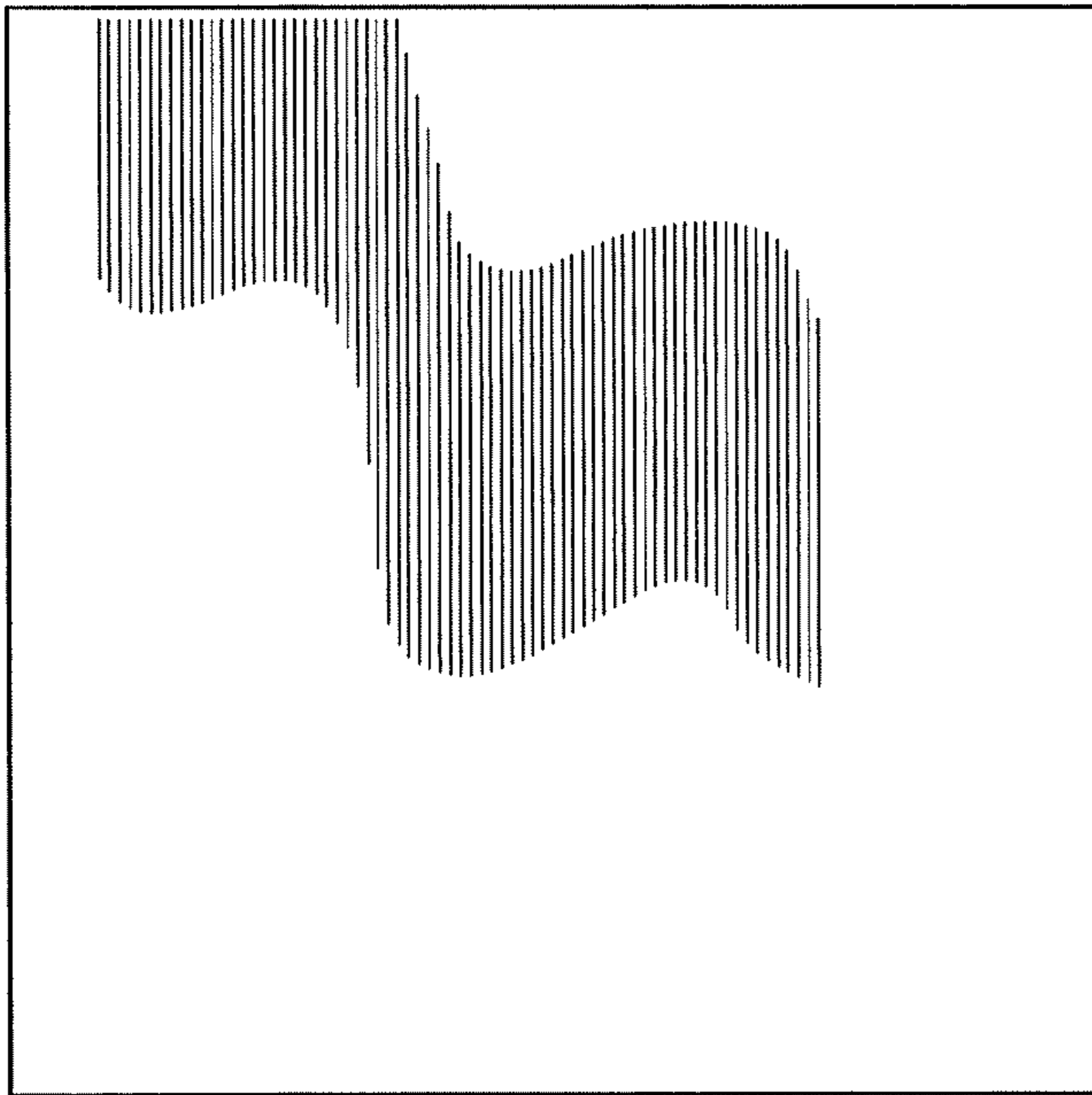


FIG. 4

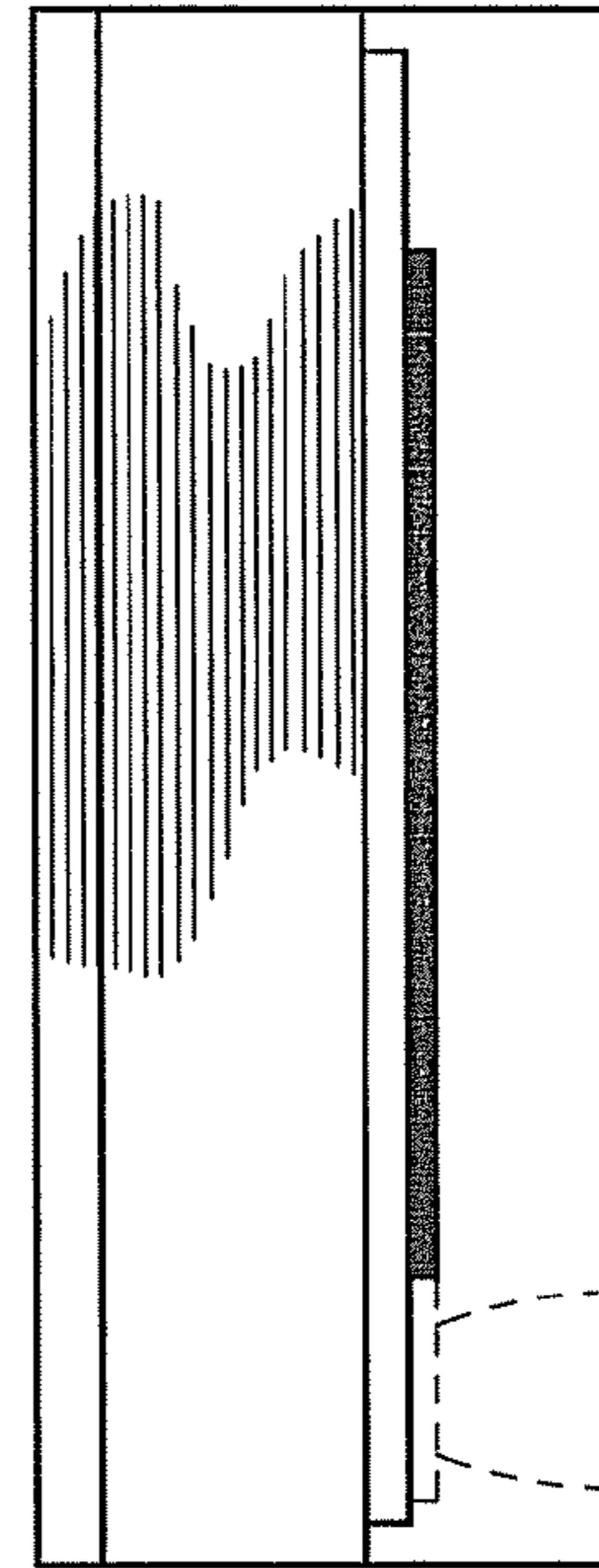


FIG. 5

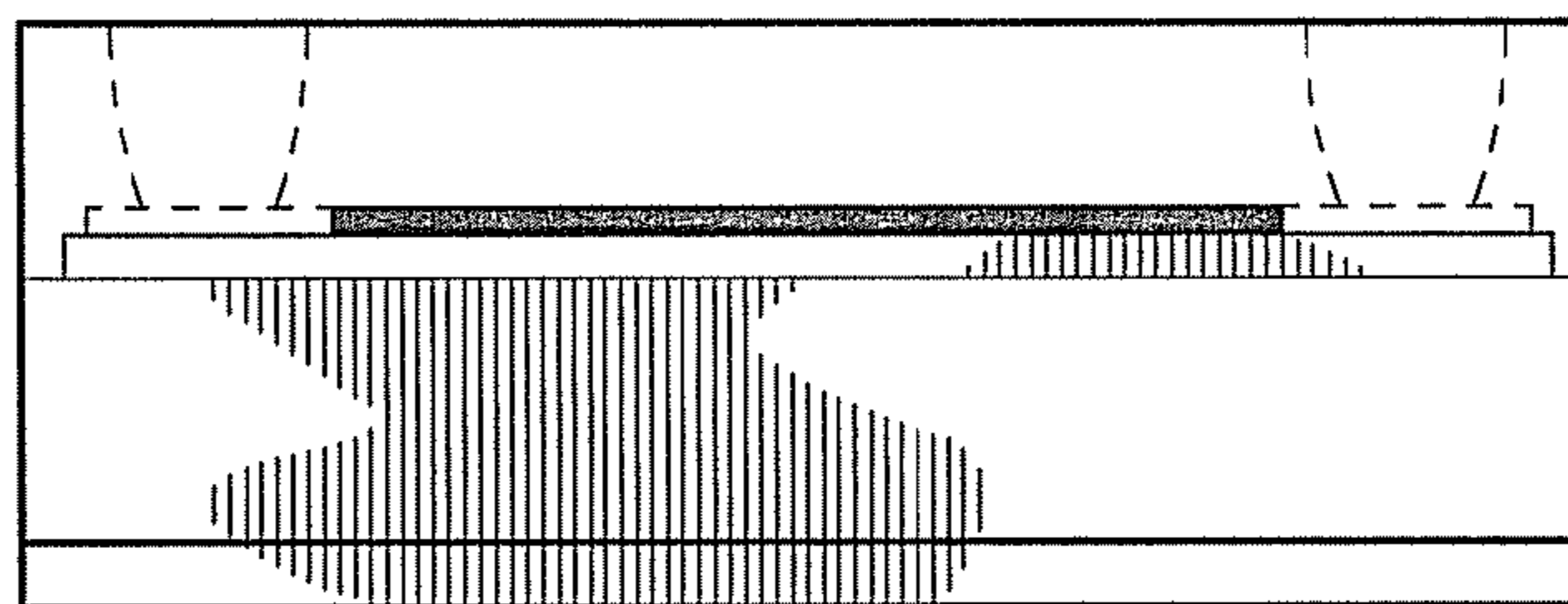


FIG. 6

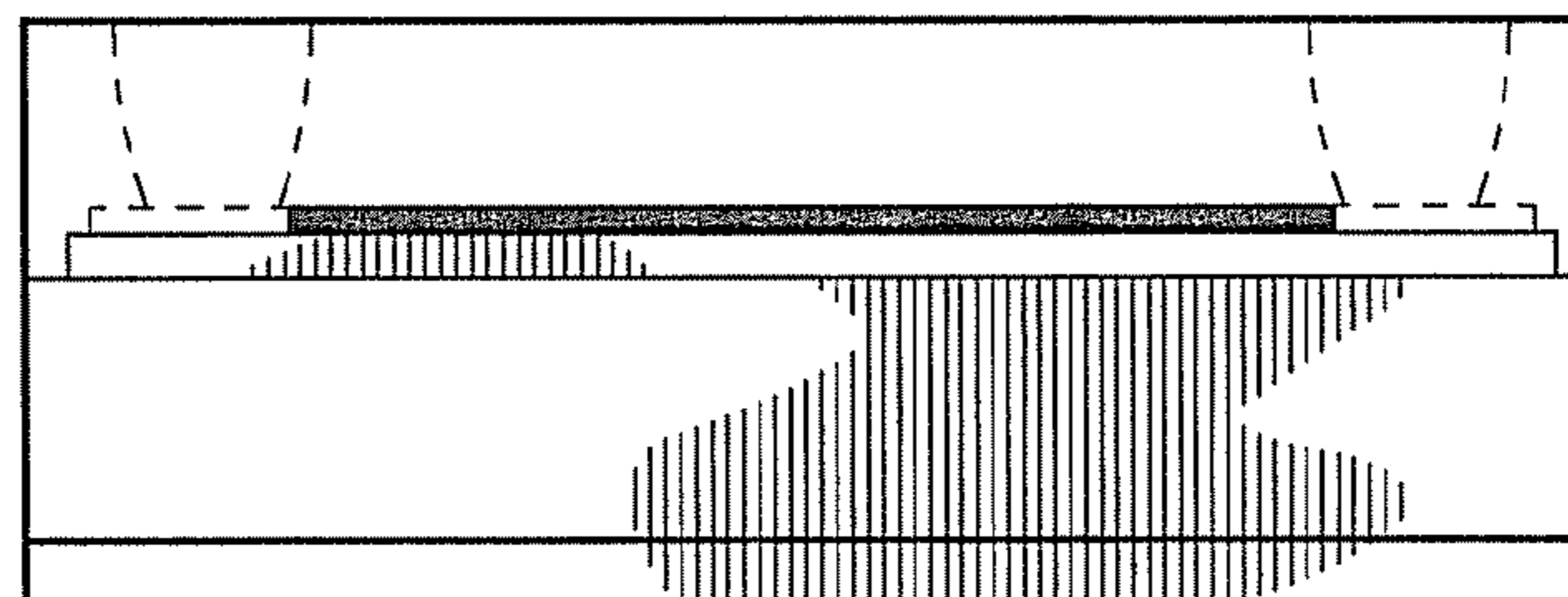


FIG. 7

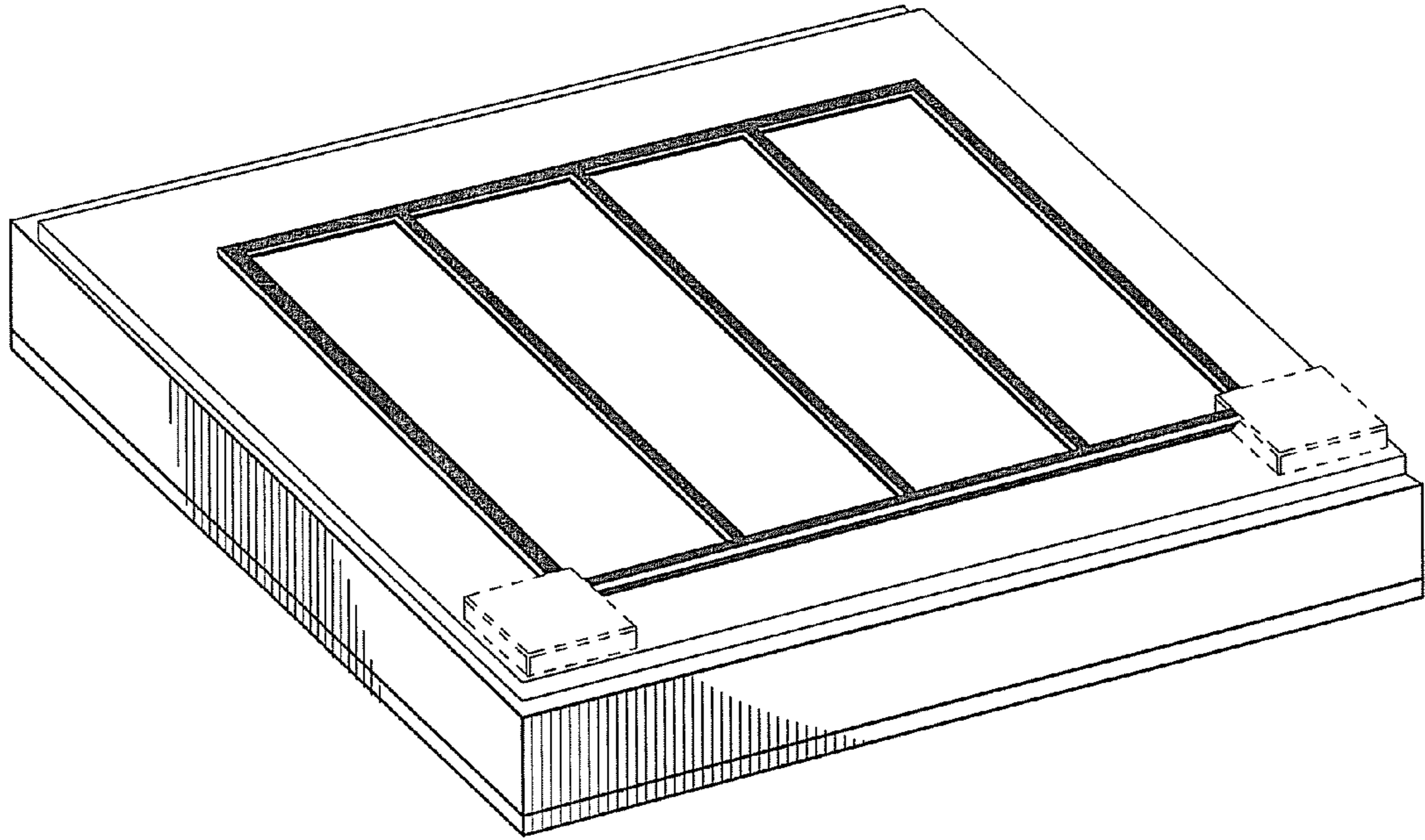


FIG. 8

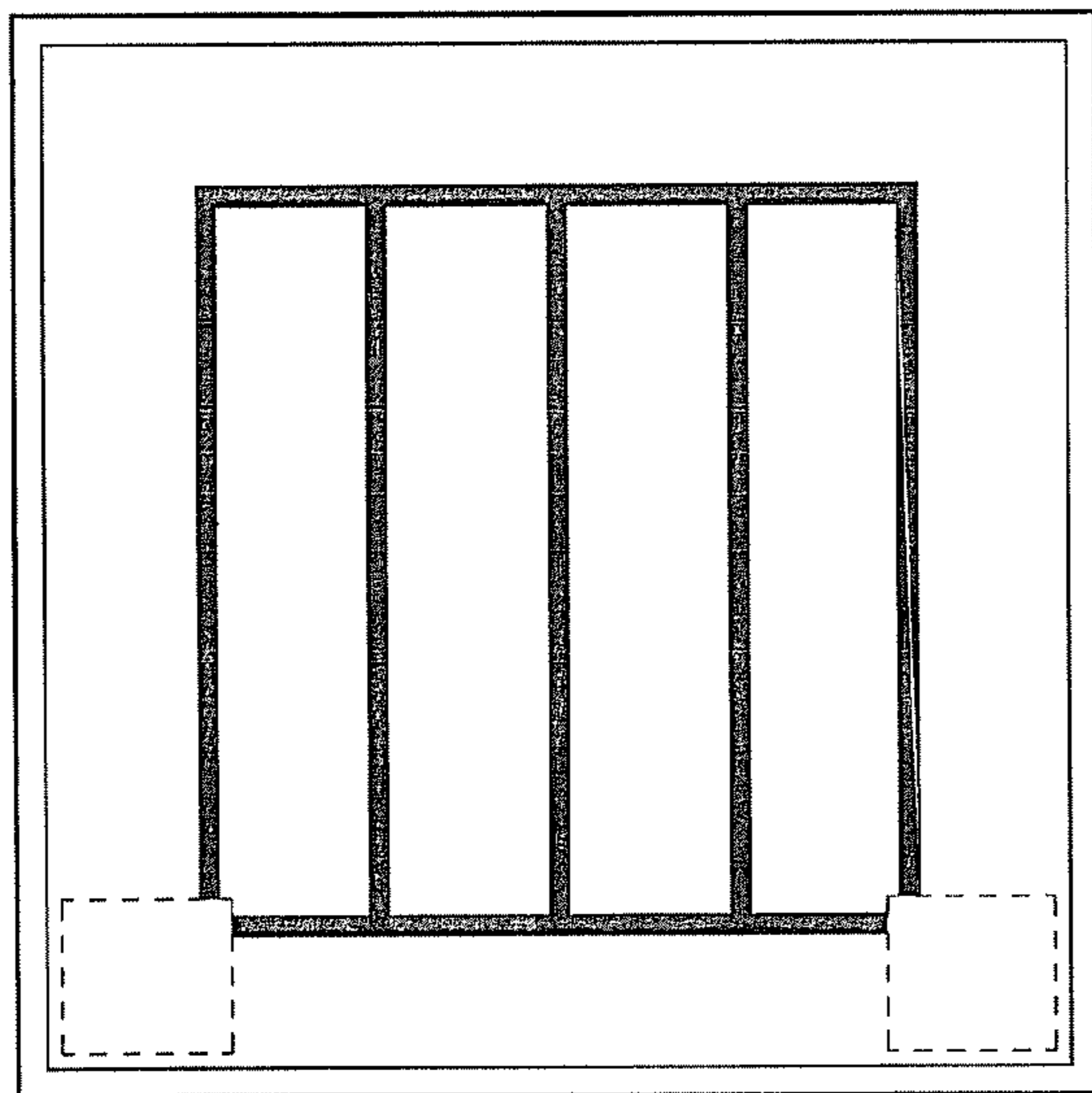


FIG. 9

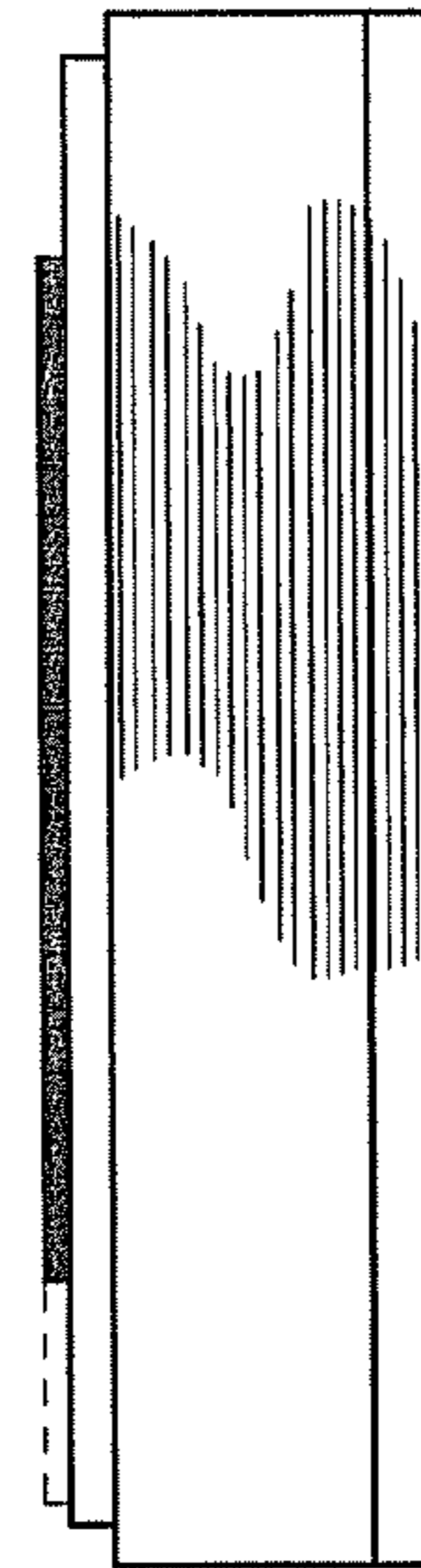


FIG. 10

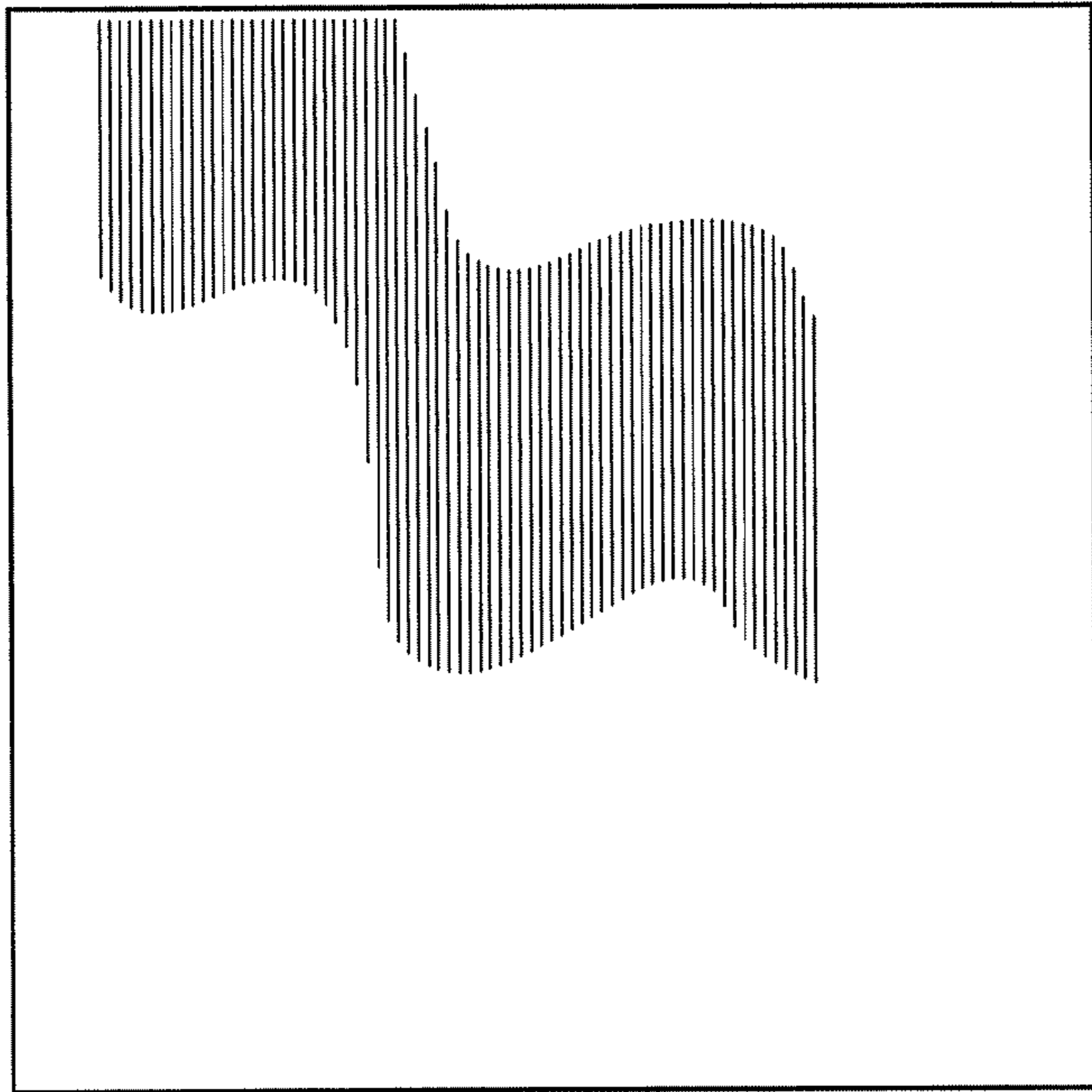


FIG. 11

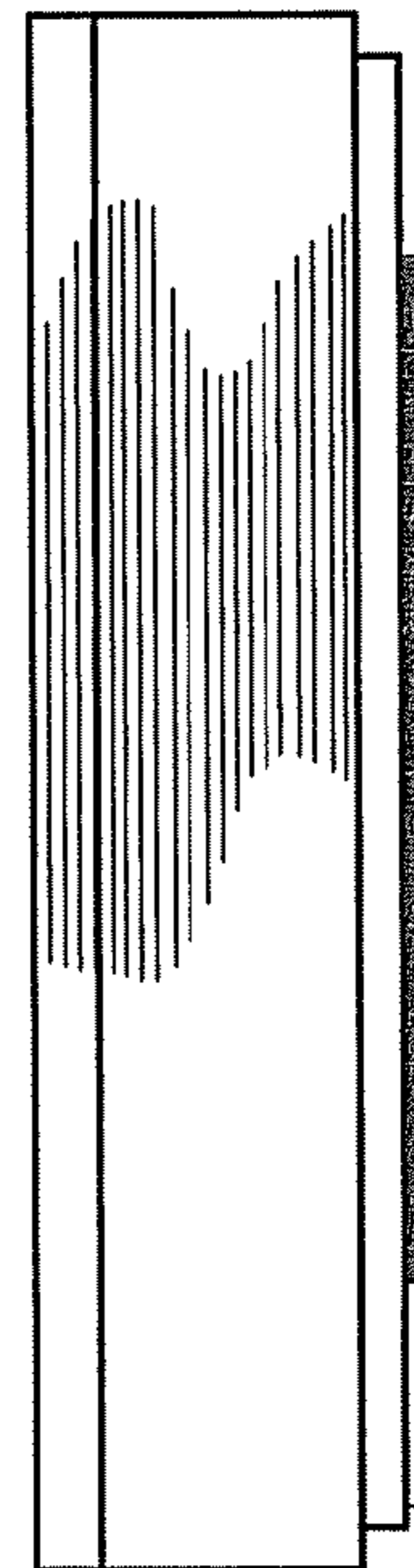


FIG. 12

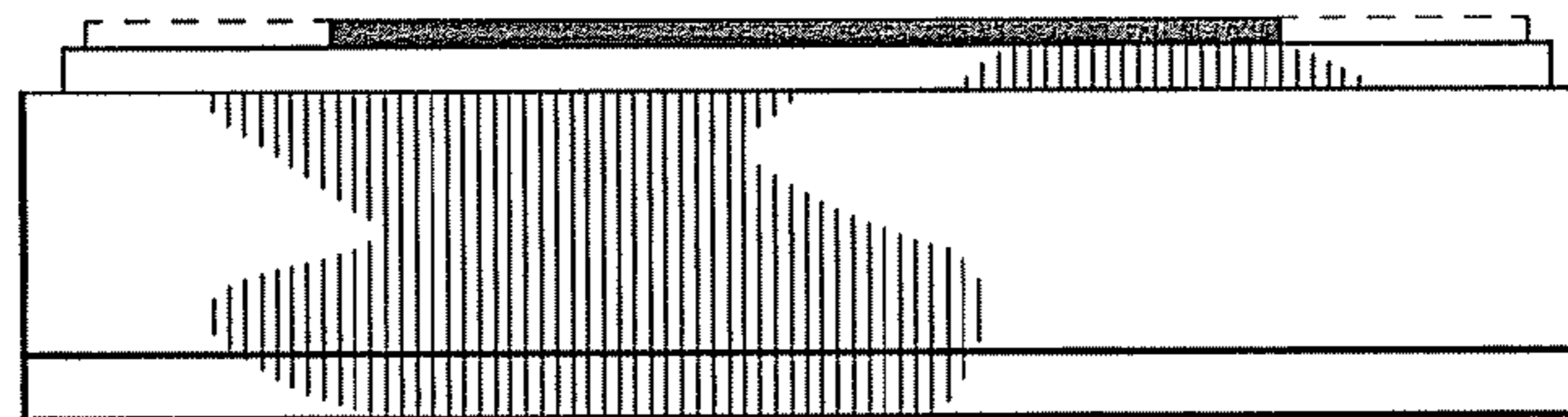


FIG. 13

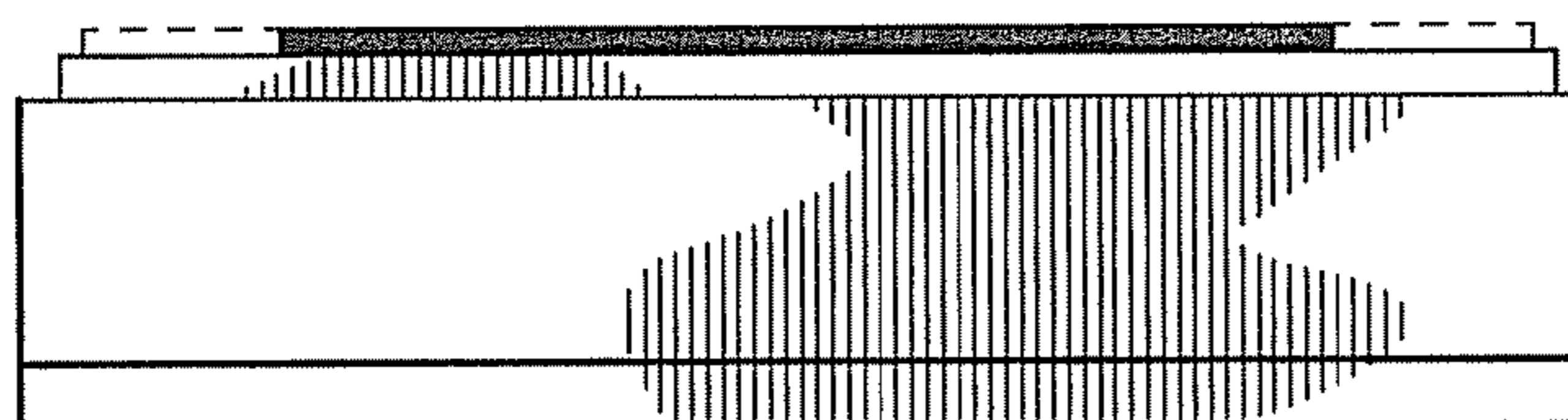


FIG. 14